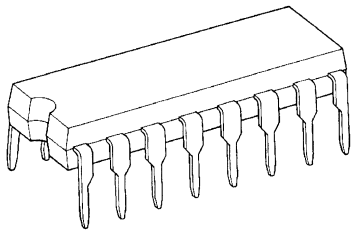
TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62318BP,TD62318BF

4CH LOW INPUT ACTIVE HIGH−CURRENT DARLINGTON SINK DRIVER

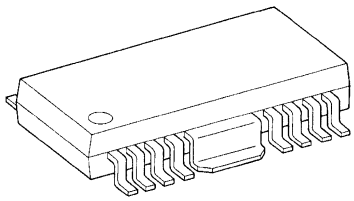
The TD62318BP and TD62318BF are non−inverting transistor array which are comprised of four NPN darlington output stages and PNP input stages.
This device is low level input active driver and are suitable for operation with TTL, 5 V CMOS and 5 V Microprocessor which have sink current output drivers.
Applications include relay, hammer, lamp and stepping motor drivers.

TD62318BP



DIP16-P-300-2.54A

TD62318BF



HSOP16-P-300-1.00

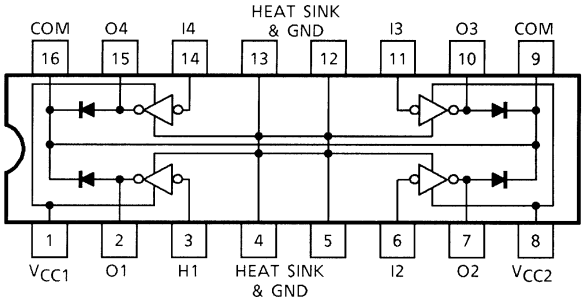
Weight
DIP16−P−300−2.54A : 1.11 g (Typ.)
HSOP16−P−300−1.00 : 0.50 g (Typ.)

FEATURES

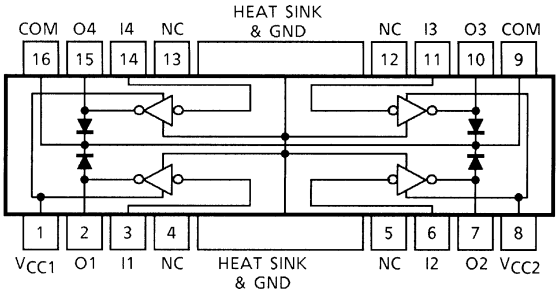
- Two V_{CC} Terminals V_{CC1}, V_{CC2} (Separated)
- Package Type BP: DIP−16 pin
  BF: HSOP−16 pin
- High Sustaining Voltage Output : $V_{CE\ (SUS)}$ = 80 V (Min.)
- Output Current (Single Output) : I_{OUT} = 700 mA / ch (Max.)
- Output Clamp Diodes
- Input Compatible with TTL and 5 V CMOS
- GND and SUB Terminal = Heat Sink
- Low Level Active Input
- Standard Supply Voltage

PIN CONNECTION (TOP VIEW)

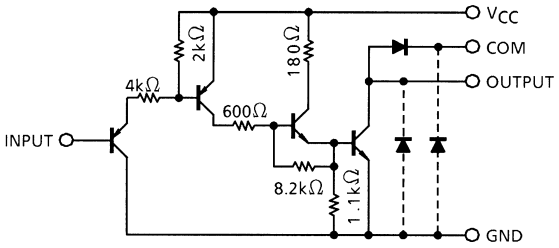
TD62318BP



TD62318BF



SCHEMATICS (EACH DRIVER)



Note: The input and output parasitic diode cannot be used as clamp diode.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Supply Voltage		V_{CC}	−0.5~17	V
Output Sustaining Voltage		$V_{CE\ (SUS)}$	−0.5~80	V
Output Current		I_{OUT}	700	mA / ch
Input Current		I_{IN}	−10	mA
Input Voltage		V_{IN}	−0.5~17	V
Clamp Diode Reverse Voltage		V_R	80	V
Clamp Diode Forward Current		I_F	700	mA
Power Dissipation	BP	P_D	1.47 / 2.7 (Note 1)	W
	BF		0.9 / 1.4 (Note 2)	
Operating Temperature		T_{opr}	−40~85	°C
Storage Temperature		T_{stg}	−55~150	°C

Note 1: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%)
Note 2: On Glass Epoxy PCB (60 × 30 × 1.6 mm Cu 30%)

RECOMMENDED OPERATING CONDITIONS (Ta = −40~85°C)

CHARACTERISTIC		SYMBOL	CONDITION		MIN	TYP.	MAX	UNIT
Supply Voltage		V_{CC}			4.5	—	5.5	V
Output Sustaining Voltage		$V_{CE\ (SUS)}$			0	—	50	V
Output Current		I_{OUT}	DC 1 circuit, Ta = 25°C		0	—	570	mA / ch
	BP (Note 1)		T_{pw} = 25 ms 4 circuits T_j = 120°C Ta = 85°C	Duty = 10%	0	—	570	
				Duty = 50%	0	—	330	
	BP (Note 2)			Duty = 10%	0	—	570	
				Duty = 50%	0	—	100	
Input Voltage		V_{IN}			0	—	15	V
	Output On	$V_{IN\ (ON)}$			0	—	V_{CC} −3.6	V
	Output Off	$V_{IN\ (OFF)}$			V_{CC} −3.6	—	5.5	
Clamp Diode Reverse Voltage		V_R			—	—	80	V
Clamp Diode Forward Current		I_F			—	—	700	mA
Power Dissipation	BP	P_D	Ta = 85°C	(Note 1)	—	—	1.4	W
	BF		Ta = 85°C	(Note 2)	—	—	0.7	

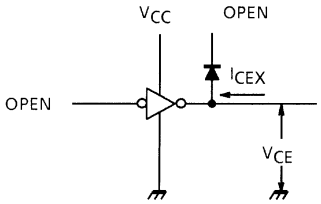
Note 1: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%)
Note 2: On Glass Epoxy PCB (60 × 30 × 1.6 mm Cu 30%)

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

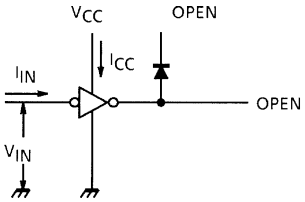
CHARACTERISTIC		SYMBOL	TEST CIR−CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Input Voltage	"H" Level	V_{IH}	—		V_{CC} −1.6	—	15	V
	"L" Level	V_{IL}			0	—	V_{CC} −3.6	
Input Current	"H" Level	I_{IH}	2		—	—	10	μA
	"L" Level	I_{IL}			—	−0.05	−0.36	mA
Output Leakage Current		I_{CEX}	1	V_{CE} = 80 V, Ta = 25°C	—	—	50	μA
				V_{CE} = 80 V, Ta = 85°C	—	—	100	
Output Saturation Voltage		$V_{CE\ (sat)}$	3	I_{OUT} = 0.5 A, V_{CC} = 4.5 V	—	—	0.8	V
				I_{OUT} = 0.2 A, V_{CC} = 4.5 V	—	—	0.45	
Clamp Diode Reverse Current		I_R	4	V_R = 80 V, Ta = 25°C	—	—	50	μA
				V_R = 80 V, Ta = 85°C	—	—	100	
Clamp Diode Forward Voltage		V_F	5	I_F = 500 mA	—	—	2.0	V
Supply Current	Output On	$I_{CC\ (ON)}$	2	V_{CC} = 5.5 V, V_{IN} = 0 V	—	35	40	mA / ch
	Output Off	$I_{CC\ (OFF)}$	2	V_{CC} = 5.5 V, V_{IN} = V_{CC}	—	—	10	μA
Turn−On Delay		t_{ON}	6	V_{OUT} = 80 V, R_L = 142 Ω V_{CC} = 5.0 V, C_L = 15 pF	—	0.4	0.8	μs
Turn−Off Delay		t_{OFF}			—	8.0	16.0	

TEST CIRCUIT

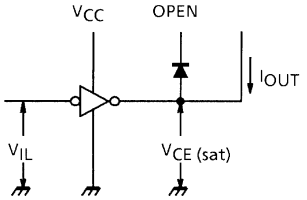
1. I_{CEX}



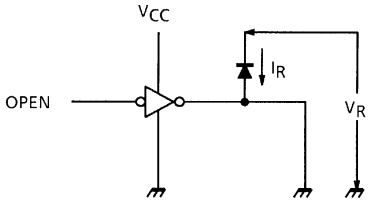
2. I_{IH}, I_{IL}



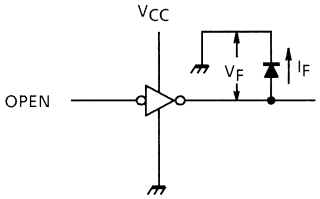
3. $V_{CE\ (sat)}$



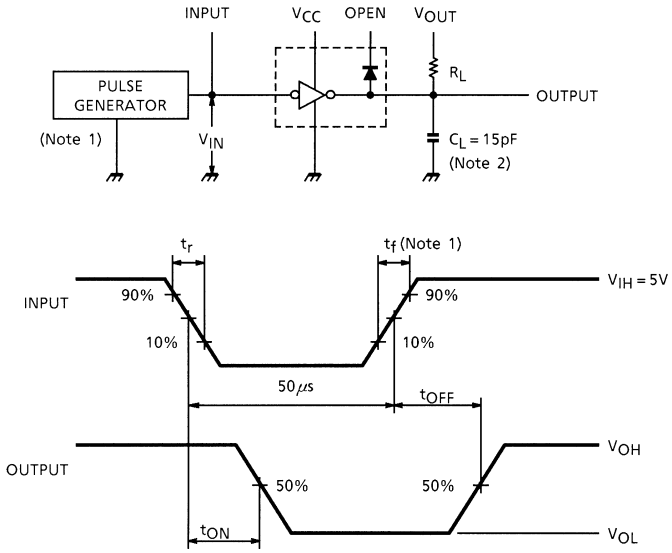
4. I_R



5. V_F



6. t_{ON}, t_{OFF}



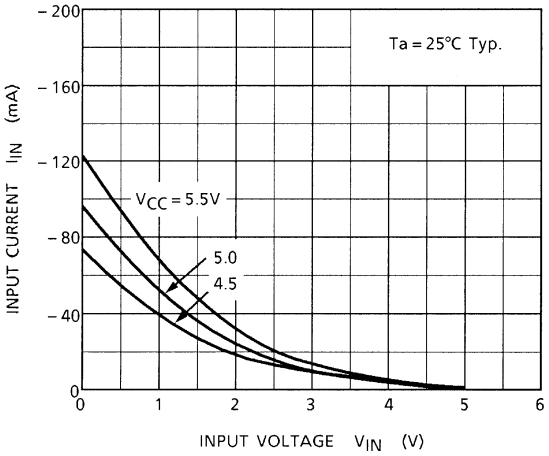
Note 1: Pulse Width 50 μs, Duty Cycle 10%
Output Impedance 50 Ω, $t_r \leq 5$ ns, $t_f \leq 10$ ns

Note 2: C_L includes probe and jig capacitance.

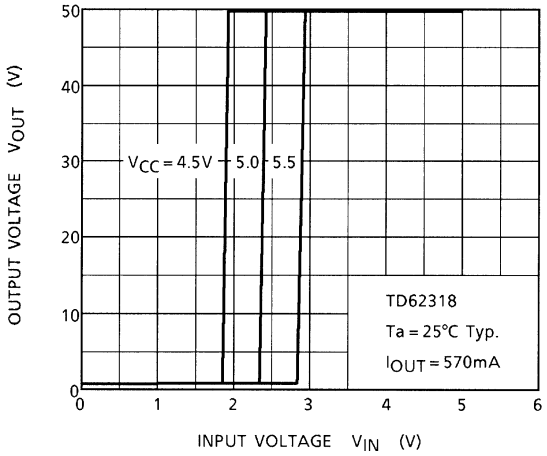
PRECAUTIONS for USING

This IC does not include built-in protection circuits for excess current or overvoltage.
If this IC is subjected to excess current or overvoltage, it may be destroyed.
Hence, the utmost care must be taken when systems which incorporate this IC are designed.
Utmost care is necessary in the design of the output line, V_{CC}, COMMON and GND line since IC may be destroyed due to short−circuit between outputs, air contamination fault, or fault by improper grounding.

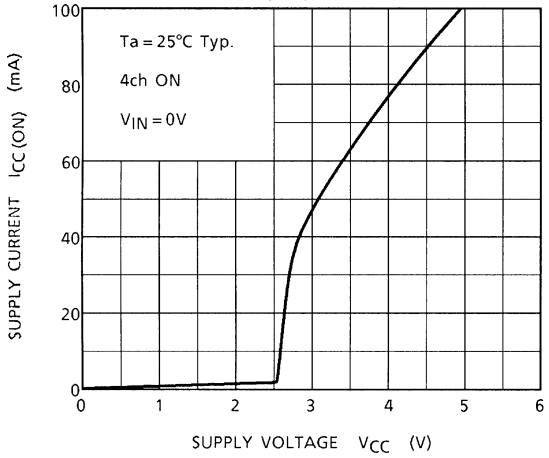
I_{IN} – V_{IN}



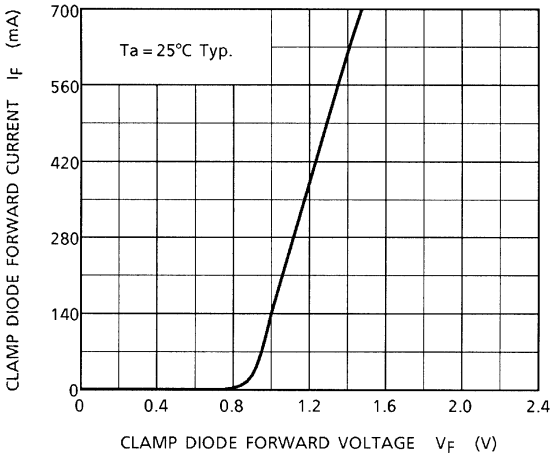
V_{OUT} – V_{IN}



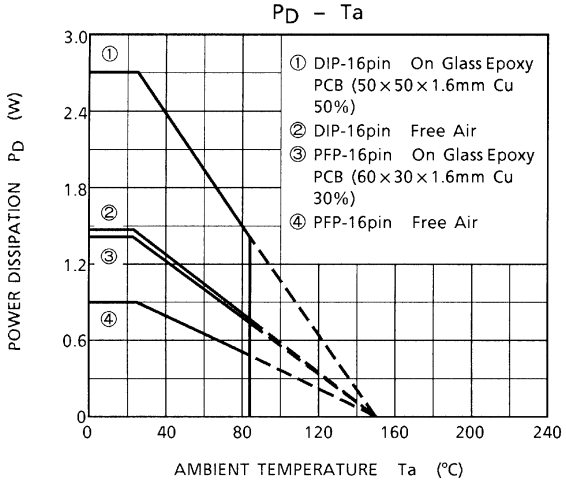
$I_{CC\,(ON)}$ – V_{CC}

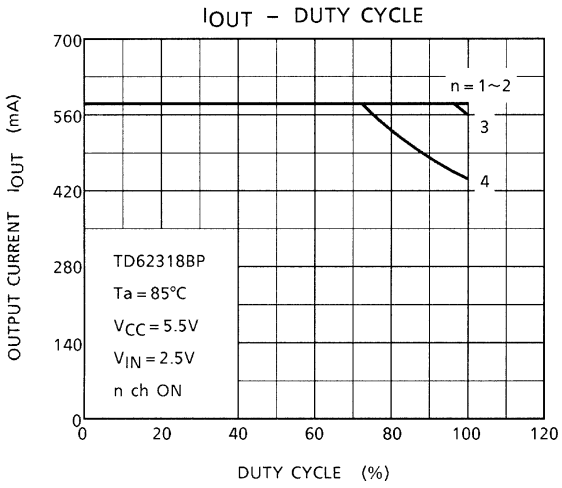


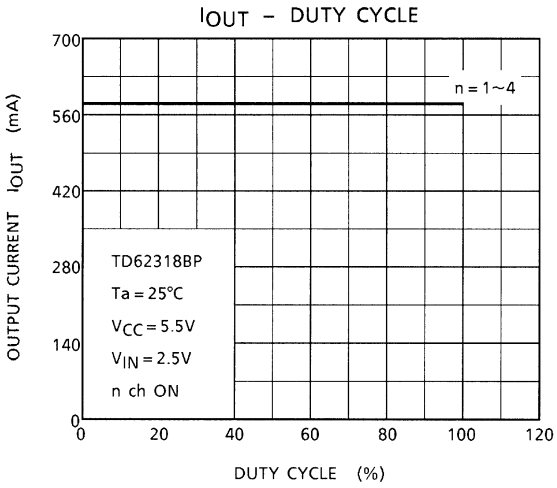
I_F – V_F

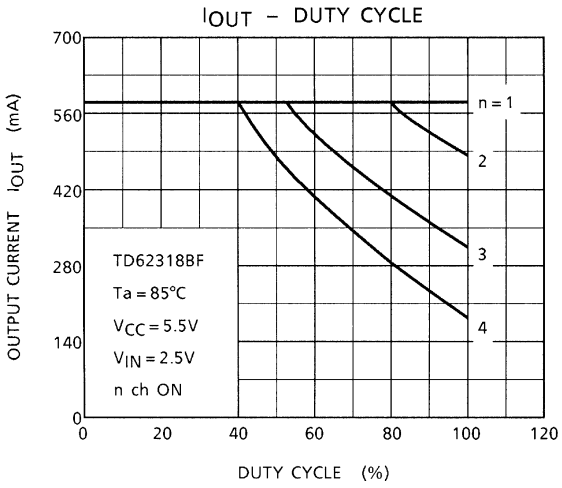


P_D – Ta




IOUT – DUTY CYCLE
OUTPUT CURRENT IOUT (mA)
DUTY CYCLE (%)
n = 1~2
3
4
TD62318BP
Ta = 85°C
VCC = 5.5V
VIN = 2.5V
n ch ON
700
560
420
280
140
0
0
20
40
60
80
100
120


IOUT – DUTY CYCLE
OUTPUT CURRENT IOUT (mA)
DUTY CYCLE (%)
n = 1~4
TD62318BP
Ta = 25°C
VCC = 5.5V
VIN = 2.5V
n ch ON
700
560
420
280
140
0
0
20
40
60
80
100
120


IOUT – DUTY CYCLE
OUTPUT CURRENT IOUT (mA)
DUTY CYCLE (%)
n = 1
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TD62318BF
Ta = 85°C
VCC = 5.5V
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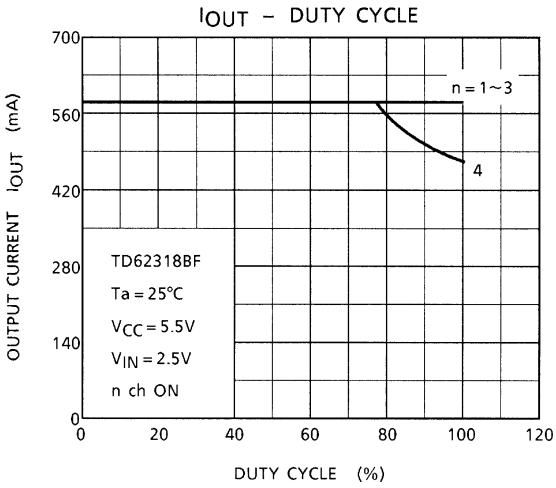
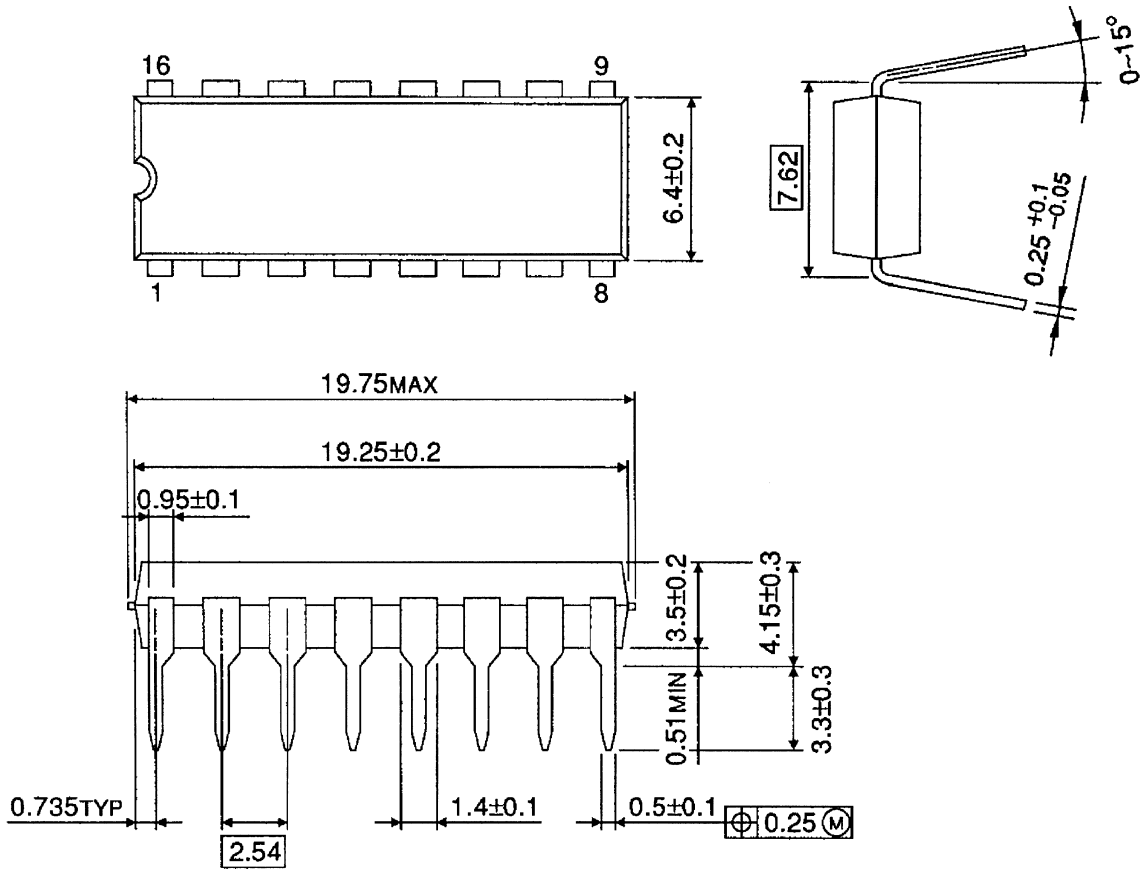
n ch ON
700
560
420
280
140
0
0
20
40
60
80
100
120


IOUT – DUTY CYCLE
OUTPUT CURRENT IOUT (mA)
DUTY CYCLE (%)
n = 1~3
4
TD62318BF
Ta = 25°C
VCC = 5.5V
VIN = 2.5V
n ch ON
700
560
420
280
140
0
0
20
40
60
80
100
120

PACKAGE DIMENSIONS

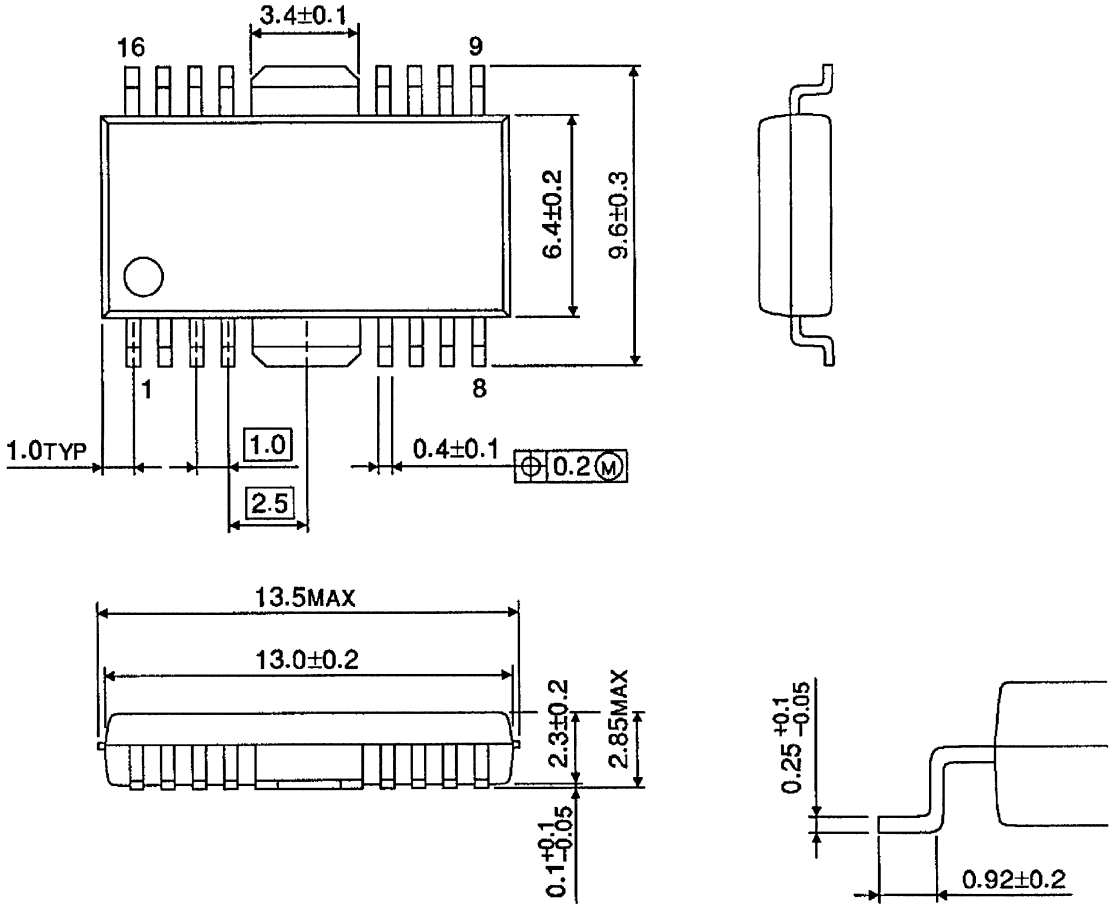
DIP16−P−300−2.54A Unit: mm



Weight: 1.11 g (Typ.)

PACKAGE DIMENSIONS

HSOP16−P−300−1.00 Unit: mm



Weight: 0.50 g (Typ.)

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